

US5834140A Electrodeposited copper foil for fine pattern and method for producing the same

Applicants: CIRCUIT FOIL JAPAN [JP]

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Abstract

The present invention is an electrodeposited copper foil characterised in that roughening treatment is performed on a matte side of an untreated copper foil wherein the surface roughness Rz of the matte side of the untreated copper foil is the same as or less than the surface roughness Rz of the shiny side of this untreated copper foil. The electrodeposited copper foil is made by electrodepositing copper onto a drum from an electrolyte which contains 0.05 to 5 ppm 3-mercapto 1-propanesulfonate; at least one organic compound selected from 0.1 to 15 ppm of a polysaccharide which is a carbohydrate such as starches, celluloses and vegetable rubbers, and 0.3 to 35 ppm of a low molecular weight glue having a weight average molecular weight of 10,000 or less; and 10 to 60 ppm of a chloride ion. The copper foil may be used in making a printed circuit board or as a component of a secondary battery cell.